### **MA27D30**

### Silicon epitaxial planar type

#### For super high speed switching

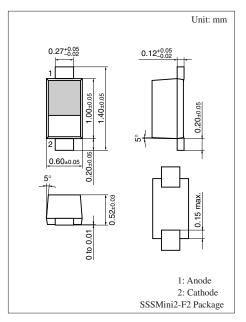
#### ■ Features

- Small reverse current:  $I_R < 2 \mu A$  (at  $V_R = 30 \text{ V}$ )
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>.

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average)	I <sub>F(AV)</sub>	100	mA
Peak forward current	$I_{FM}$	200	mA
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	A
Junction temperature	Tj	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



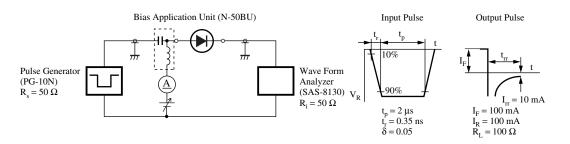
Marking Symbol: 8N

#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

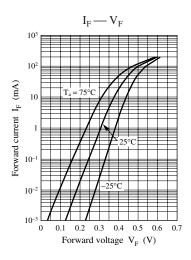
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 10 \text{ mA}$		0.38	0.44	V
	$V_{F2}$	$I_F = 100 \text{ mA}$		0.51	0.58	V
Reverse current	I <sub>R1</sub>	$V_R = 10 \text{ V}$			0.3	μΑ
	$I_{R2}$	$V_R = 30 \text{ V}$			2	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$		9		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_{L} = 100 \Omega$				

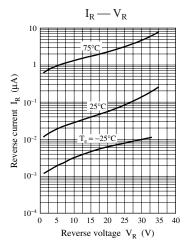
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

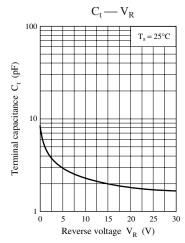
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz
- 4. \*: t<sub>rr</sub> measurement circuit



# **Panasonic**







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